12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260213000.1
Qualification of LFAB as an additional fab site and PHI as additional Assembly site for Select Devices
Change Notification / Sample Request

Date: February 19, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260213000.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
IWR2944AQGALTR	NULL
IWR2944ABGALTR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260213000.1	**PCN Date:**	February 19, 2026
Title:	Qualification of LFAB as an additional fab site and PHI as additional Assembly site for Select Devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	May 20, 2026	**Sample requests accepted until:**	April 20, 2026

***Sample requests received after** April 20, 2026 **will not be supported.**

Change Type:

☒ Assembly Site	☐ Design	☐ Wafer Bump Material
☐ Assembly Process	☒ Data Sheet	☐ Wafer Bump Process
☐ Assembly Materials	☐ Part number change	☒ Wafer Fab Site
☐ Mechanical Specification	☐ Test Site	☒ Wafer Fab Materials
☒ Packing/Shipping/Labeling	☐ Test Process	☐ Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of LFAB as an additional fab site and PHI as additional Assembly site for the devices listed below in the product affected section.

Process Step	Current	Current New	Additional
Wafer Fab Site	UMC-F12	UMC-F12	LFAB
Metallization (METTOP)	12.6kA	17.7kA	17.7kA

Process Step	Current	Additional
Assembly Site	ANA	PHI

(No material differences between sites)

Qual details are provided in the Qual Data Section.

The datasheet will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

TEXAS INSTRUMENTS — IWR2944
SWRS330A – MAY 2024 – REVISED FEBRUARY 2026

Changes from May 31, 2024 to February 28, 2026 (from Revision (May 2024) to Revision (February 2026)) — **Page**

- Updated ESD ratings for GPADC5 and GPADC6 34

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
IWR2944	SWRS330	**SWRS330A**	http://www.ti.com/product/IWR2944

Reason for Change:

Capacity increase to support demand and continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

No anticipated impact.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
UMC-F12	F12	TWN	TAINAN
LFAB	**LHI**	**USA**	**Lehi**

Assembly Site Information:

Assembly Site	Assembly Site Origin Code (22L)	Assembly Site Country Code (23L)	Assembly Site City
ANA	AMP	KOR	Gwangju
PHI	**PHI**	**PHL**	**Baguio City**

Sample product shipping label (not actual product label):

Product Affected:

IWR2944ABGALTR	IWR2944ABSALTR	IWR2944AQGALTR
IWR2944ABSALT	IWR2944AQGALT	

Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)

AWR294x TI Lehi (LFAB) Qualification with Amkor K5 Bump and K4 Assembly
Approve Date 11-February-2026

Product Attributes

Attributes	Qual Device: AWR2944ABGALTRQ1	QBS Product Reference: AWR1843ABGABLRQ1	QBS Product Reference: AWR2F44ABSALLRQ1
Automotive Grade Level	Grade 2	Grade 2	Grade 1
Operating Temp Range (C)	-40 to 125C Tj	-40 to 125C Tj	-40 to 140C Tj
Product Function	Microprocessor	Microprocessor	Microprocessor
Die Attributes			
Wafer Fab Supplier	LFAB	LFAB	LFAB
Wafer Process	1118C014.M8	1118C014.M8	1118C014.M8
Package Attributes			
Assembly Site	ANA	ANA	ANA
Package Group	FCCSP	FCCSP	FCCSP
Package Designator	ALT	ABL	ALL
Package Size (mm)	12 x 12	10.4 x 10.4	14 x 14
Body Thickness (mm)	0.75	0.75	1.09
Pin Count	266	161	311
Lead Finish	SNAGCU	SNAGCU	SNAGCU

QBS: Qual By Similarity, also known as Generic Data
Qual Device AWR2944ABGALTRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AWR2944ABGALTRQ1	QBS Product Reference: AWR1843ABGABLRQ1	QBS Product Reference: AWR2F44ABSALLRQ1
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J- STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	3/540/0	-	3/231/0
HAST	A2	JEDEC JESD22-A110	3	77	Temperature Humidity Bias	85C/85%RH	1000 Hours	-	-	3/231/0
AC/UHAST	A3	JEDEC JESD22A102/JEDEC JESD22-A118	3	77	Unbiased HAST	110C/85%RH	264 Hours	3/231/0	-	-
TC	A4	JEDEC JESD22A104 and Appendix 3	3	77	Temperature Cycle	-55C/150C	1000 Cycles	3/231/0	-	-
Type	**#**	**Test Spec**	**Min Lot Qty**	**SS / Lot**	**Test Name**	**Condition**	**Duration**	**Qual Device: AWR2944ABGALTRQ1**	**QBS Product Reference: AWR1843ABGABLRQ1**	**QBS Product Reference: AWR2F44ABSALLRQ1**
HTSL	A6	JEDEC JESD22A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	1/45/0
Test Group B - Accelerated Lifetime Simulation Tests										

HTOL	B1	JEDEC JESD22A108	3	77	Life Test	140C Tj	1000 Hours	-	-	3/231/0
ELFR	B2	AEC Q100008	3	800	Early Life Failure Rate	140C Tj	48 Hours	-	3/2400/0	1/800/0
Test Group C - Package Assembly Integrity Tests										
PD	C4	JEDEC JESD22B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	-
Test Group D - Die Fabrication Reliability Tests										
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests										
ESD	E2	AEC Q100002	1	3	ESD HBM	-	2000 Volts	1/3/0	-	-
ESD	E3	AEC Q100011	1	3	ESD CDM	-	500 Volts	1/3/0	-	-
ESD	E3	AEC Q100011	1	3	ESD CDM	Corner pins	750 Volts	1/3/0	-	-
LU	E4	AEC Q100004	1	3	Latch-Up	Per AEC Q100-004	-	-	-	1/3/0
ED	E5	AEC Q100009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	-	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C Grade 2
(or T): -40C to +105C Grade 3 (or I) : 40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ TI
TI Qualification ID: R-CHG-2501-007

Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)

AWR2944 ETS (266 ALT) TIPI ES2.0
Approve Date 11-February-2026

Product Attributes

Attributes	Qual Device: AWR2944ABGALTQ1	QBS Reference: AWR2944ABGALTQ1	QBS Reference: AWR2G44ABSALLRQ1	QBS Reference: AWR2943ABGALTQ1	QBS Reference: AWR2944ABGALTQ1
Automotive Grade Level	Grade 2	Grade 2	Grade 1	Grade 2	Grade 2
Operating Temp Range (C)	-40 to 125 Tj	-40 to 125 Tj	-40 to 140C Tj	-40 to 125C Tj	-40 to 125C Tj
Product Function	Microprocessor	Microprocessor	Microprocessor	Microprocessor	Microprocessor
Die Attributes					
Wafer Fab Supplier	UMCI	UMCI	UMCI	UMCI	UMCI
Wafer Process	1118C014.M8	1118C014.M8	1118C014.M8	1118C014.M8	1118C014.M8
Package Attributes					
Assembly Site	PHI	ANA	PHI	PHI	PHI (alternate substrate vendor)
Package Group	FCCSP	FCCSP	FCCSP	FCCSP	FCCSP
Package Designator	ALT	ALT	ALL	ALT	ALT
Package Size (mm)	12 x 12	12 x 12	14 x 14	12 x 12	12 x 12
Body Thickness (mm)	0.75	0.75	1.09	0.75	0.75
Pin Count	266	266	311	266	266
Lead Finish	SNAGCU	SNAGCU	SNAGCU	SNAGCU	SNAGCU
Lead Pitch(mm)	0.65	0.65	0.65	0.65	0.65

QBS: Qual By Similarity, also known as Generic Data
Qual Device AWR2944ABGALTQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AWR2944ABGALTQ1	QBS Reference: AWR2944ABGALTQ1	QBS Reference: AWR2G44ABSALLRQ1	QBS Reference: AWR2944ABGALTQ1 (PHI, alternative substrate vendor)
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	3/540/0	3/300/0	3/990/0	3/231/0

HAST	A2	JEDEC JESD22A110	3	77	Temperature Humidity Bias	85C/85%RH	1000 Hours	-	-	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22A102/JEDEC JESD22-A118	3	77	Unbiased HAST	110C/85%RH	264 Hours	3/231/0	-	-	
TC	A4	JEDEC JESD22A104 and Appendix 3	3	77	Temperature Cycle	-55C/150C	1000 Cycles	3/231/0	3/231/0	3/231/0	
HTSL	A6	JEDEC JESD22- A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/78/0	3/78/0
Test Group B - Accelerated Lifetime Simulation Tests											
HTOL	B1	JEDEC JESD22A108	3	77	Life Test	125C	1000 Hours	3/231/0	-	-	
ELFR	B2	AEC Q100008	3	800	Early Life Failure Rate	125C	48 Hours	3/2400/0	-	-	
Test Group C - Package Assembly Integrity Tests											
Test Group D - Die Fabrication Reliability Tests											
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests											
ESD	E2	AEC Q100002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	-	
ESD	E3	AEC Q100011	1	3	ESD CDM	-	500 Volts	1/3/1* (1/3/0 at 450V)	1/3/0	-	
ESD	E3	AEC Q100011	1	3	ESD CDM	-	750 Volts (Corner Pins only)	1/3/0			
LU	E4	AEC Q100004	1	3	Latch-Up	Per AEC Q100-004	-	-	1/6/0	-	

ED	E5	AEC Q100009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	3/90/0	3/90	
Additional Tests											
BLR	T1	-	-	-	Board Level Reliability - Temp Cycle	-40C/125C	1000 Cycles	1/48/0	-	1/48	

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours The following
- are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

*500V failure on GPADC5 and GPADC6 pins only. All other pins pass 500V. 8D Report for 500V GPADC pin failures available upon request.

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C Grade 2
(or T): -40C to +105C Grade 3 (or I) : 40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ TI
TI Qualification ID: R-CHG-2306-052

Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)

AWR2944 ETS (266 ALT) Thick Al METTOP (17.7kA)
Approve Date 12-FEBRUARY -2026

Product Attributes

Attributes	Qual Device: AWR2944ABGALTQ1
Automotive Grade Level	Grade 2
Operating Temp Range (C)	-40 to 125
Product Function	Microprocessor
Die Attributes	
Wafer Fab Supplier	UMCI
Wafer Process	1118C014.M8
Package Attributes	
Assembly Site	ANA
Package Group	FCCSP
Package Designator	ALT
Package Size (mm)	12 x 12
Body Thickness (mm)	0.75
Pin Count	266
Lead Finish	SNAGCU
Lead Pitch(mm)	0.65

QBS: Qual By Similarity, also known as Generic Data
Qual Device AWR2944ABGALTQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AWR2944ABGALTQ1
Test Group A - Accelerated Environment Stress Tests								
PC	A1	JEDEC J-STD-020 JESD22A113	3	77	Preconditioning	MSL3 260C	-	3/300/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-55C/150C	1000 Cycles	3/231/0
Test Group B - Accelerated Lifetime Simulation Tests								
Test Group C - Package Assembly Integrity Tests								
Test Group D - Die Fabrication Reliability Tests								
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests								
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ TI Qualification ID: R-CHG-2308-046
TI Qualification ID: R-CHG-2308-046

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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